

| L Number | Hits | Search Text | DB | Time stamp |
|----------|-------|-----------------------------------------------------------------------------------------------------------------|---------------------------------------------|------------------|
| 1 | 370 | (257/735).CCLS. | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2002/07/01 08:37 |
| 3 | 136 | (257/736).CCLS. | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2002/07/01 08:46 |
| 4 | 1748 | (257/758).CCLS. | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2002/07/01 09:43 |
| 5 | 0 | ("4 and (MCM or (chip on chip or (layered or stacked))))".PN. | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2002/07/01 09:29 |
| 7 | 816 | ((257/758).CCLS.) and (MCM or (chip on chip or (layered or stacked))) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2002/07/01 09:38 |
| 8 | 575 | ((((257/758).CCLS.) and (MCM or (chip on chip or (layered or stacked)))) and (MCM or chip on chip)) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2002/07/01 09:39 |
| 9 | 706 | (257/777).CCLS. | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2002/07/01 09:44 |
| 10 | 0 | ((257/777).CCLS.) and "cirucuit board" | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2002/07/01 09:45 |
| 11 | 278 | ((257/777).CCLS.) and "circuit board" | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2002/07/01 10:12 |
| 14 | 44787 | "circuit board" and chip | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2002/07/01 10:17 |
| 15 | 22360 | ("circuit board" and chip) and (wiring or pattern) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2002/07/01 10:17 |
| 16 | 5024 | ((("circuit board" and chip) and (wiring or pattern)) and (solder and (copper or cu))) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2002/07/01 10:18 |
| 17 | 3568 | ((("circuit board" and chip) and (wiring or pattern)) and (solder and (copper or cu))) and (resin or polyimide) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2002/07/01 10:18 |

| | | | | |
|----|------|----------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|---------------------------------------------|------------------|
| 18 | 2469 | ((("circuit board" and chip) and (wiring or pattern)) and (solder and (copper or cu)) and (resin or polyimide)) and (ball or bump) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2002/07/01 10:19 |
| 19 | 2208 | ((("circuit board" and chip) and (wiring or pattern)) and (solder and (copper or cu)) and (resin or polyimide)) and (ball or bump) and (via or hole) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2002/07/01 10:19 |
| 20 | 2111 | ((("circuit board" and chip) and (wiring or pattern)) and (solder and (copper or cu)) and (resin or polyimide)) and (ball or bump) and (via or hole) and (layer or (layered or (stack or stacked))) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2002/07/01 10:20 |
| 21 | 1959 | ((("circuit board" and chip) and (wiring or pattern)) and (solder and (copper or cu)) and (resin or polyimide)) and (ball or bump) and (via or hole) and (layer or (layered or (stack or stacked)))) and (film or (flexible or thin)) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2002/07/01 10:21 |
| 22 | 778 | ((("circuit board" and chip) and (wiring or pattern)) and (solder and (copper or cu)) and (resin or polyimide)) and (ball or bump) and (via or hole) and (layer or (layered or (stack or stacked)))) and (film or (flexible or thin)) and (tcp or tab) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2002/07/01 10:22 |
| 23 | 720 | ((("circuit board" and chip) and (wiring or pattern)) and (solder and (copper or cu)) and (resin or polyimide)) and (ball or bump) and (via or hole) and (layer or (layered or (stack or stacked))) and (film or (flexible or thin)) and (tcp or tab)) and substrate | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2002/07/01 10:28 |
| 24 | 285 | ((("circuit board" and chip) and (wiring or pattern)) and (solder and (copper or cu)) and (resin or polyimide)) and (ball or bump) and (via or hole) and (layer or (layered or (stack or stacked))) and (film or (flexible or thin)) and (tcp or tab)) and substrate and (chip near4 (stack or (stacked or (layer or layered)))) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2002/07/01 10:30 |

EAST - [silicone compounds.wsp:1] [] [] []

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(44787) "circuit" [Online Documentation]

(22360) ("circuit board" and chip) and (wiring or pattern)

(5024) ("circuit board" and chip) and (wiring or pattern) and (solder and (copper or cu))

(3568) ("circuit board" and chip) and (wiring or pattern) and (solder and (copper or cu))...

(2469) ("circuit board" and chip) and (wiring or pattern) and (solder and (copper or cu))...

(2208) (((("circuit board" and chip) and (wiring or pattern)) and (solder and (copper or cu))...

(2111) (((("circuit board" and chip) and (wiring or pattern)) and (solder and (copper or cu))...

(1959) (((("circuit board" and chip) and (wiring or pattern)) and (solder and (copper or cu))...

(778) (((("circuit board" and chip) and (wiring or pattern)) and (solder and (copper or cu))...

(720) (((("circuit board" and chip) and (wiring or pattern)) and (solder and (copper or cu))...

(285) (((((("circuit board" and chip) and (wiring or pattern)) and (solder and (copper or cu))...

(3) ("5534466").PN.

(3) ("4812191").PN.

(121) [257/748].CCLS.

(310) [257/781].CCLS.

(862) [257/750].CCLS.

(342) [257/684].CCLS.

(911) [257/686].CCLS.

[Search] [List] [Browse] [Queue] [Clear]
DBs: USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM
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257/686

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| U | I | Document ID | Issue Date | Pages | Title | Current OR | Current XRef |
|---|--------------------------|-------------------|------------|-------|---------------------------------------------------------------------------------------|------------|----------------------|
| 1 | <input type="checkbox"/> | US 20020079568 A1 | 20020627 | 11 | Stacked module package | 257/686 | |
| 2 | <input type="checkbox"/> | US 20020079567 A1 | 20020627 | 10 | PACKAGE STRUCTURE STACKING CHIPS ON FRONT SURFACE AND BACK SURFACE | 257/685 | 257/686; 257/723; |
| 3 | <input type="checkbox"/> | US 20020074639 A1 | 20020620 | 9 | Semiconductor module with improved solder joint reliability | 257/686 | 257/675; 257/706 |
| 4 | <input type="checkbox"/> | US 20020074638 A1 | 20020620 | 22 | MULTI-CHIP SEMICONDUCTOR PACKAGE STRUCTURE | 257/686 | 257/724 |
| 5 | <input type="checkbox"/> | US 20020074637 A1 | 20020620 | 13 | Stacked flip chip assemblies | 257/686 | 257/723; 257/737; |
| 6 | <input type="checkbox"/> | US 20020070438 A1 | 20020613 | 12 | Multi-chip stack and method of fabrication utilizing self-aligning electrical contact | 257/685 | 257/686; 257/737; |
| 7 | <input type="checkbox"/> | US 20020066952 A1 | 20020606 | 17 | Semiconductor device having an interconnecting post formed on an | 257/698 | 257/686; 257/701 |

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EAST - [silicone compounds.wsp:1]

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[342] (257/684).CCLS.
 (911) (257/686).CCLS.
 (796) "beam lead" and defin\$
 (445) ("beam lead" and defin\$) and [TCP o
 (100) ("beam lead" and defin\$) and [TCP o
 (71) ((("beam lead" and defin\$) and [TCP o
 (58) (((("beam lead" and defin\$) and [TCP o
 (50) (((("beam lead" and defin\$) and [TCP o

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Tagged (0)

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DBs USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB Plurals

Default operator: OR Highlight all hit terms initially

((((("beam lead" and defin\$) and [TCP or (tape or film)]) and "circuit board") and (via or hole)) and metal) and substrate

BRS form IS&R form Image Text HTML

| | U | 1. | Document ID | Issue Date | Pages | Title | Current OR | Current XRef |
|----|--------------------------|--------------------------|-------------------|------------|-------|----------------------------------------------------------------------------------|------------|----------------------|
| 1 | <input type="checkbox"/> | <input type="checkbox"/> | US 20020041027 A1 | 20020411 | 25 | Semiconductor device | 257/737 | 438/613 |
| 2 | <input type="checkbox"/> | <input type="checkbox"/> | US 20020030261 A1 | 20020314 | 7 | Multi-flip-chip semiconductor assembly | 257/685 | 438/108 |
| 3 | <input type="checkbox"/> | <input type="checkbox"/> | US 20020018101 A1 | 20020214 | 21 | Inkjet printhead for wide area printing | 347/56 | |
| 4 | <input type="checkbox"/> | <input type="checkbox"/> | US 20020015073 A1 | 20020207 | 21 | Inkjet printhead for wide area printing | 347/42 | |
| 5 | <input type="checkbox"/> | <input type="checkbox"/> | US 20010054756 A1 | 20011227 | 13 | Multi-layered semiconductor device and method for producing the same | 257/678 | 438/106; 438/121 |
| 6 | <input type="checkbox"/> | <input type="checkbox"/> | US 20010053563 A1 | 20011220 | 10 | Method for manufacturing a chip scale package having slits formed on a substrate | 438/106 | 438/127; 438/613 |
| 7 | <input type="checkbox"/> | <input type="checkbox"/> | US 20010001989 A1 | 20010531 | 32 | Microelectronic connections with liquid conductive elements | 174/52.1 | 29/835; 29/840; |
| 8 | <input type="checkbox"/> | <input type="checkbox"/> | US 6392143 B1 | 20020521 | 30 | Flexible package having very thin semiconductor chip, module and multi chip | 174/52.4 | 174/254; 174/260; |
| 9 | <input type="checkbox"/> | <input type="checkbox"/> | US 6388336 B1 | 20020514 | 9 | Multipchip semiconductor assembly | 257/779 | 257/666; 257/690; |
| 10 | <input type="checkbox"/> | <input type="checkbox"/> | US 6355981 B1 | 20020312 | 37 | Wafer fabrication of inside-wrapped contacts for electronic devices | 257/735 | 257/693; 257/702; |
| 11 | <input type="checkbox"/> | <input type="checkbox"/> | US 6329607 B1 | 20011211 | 20 | Microelectronic lead structures with | 174/261 | 228/180.21; |

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